

Title (en)  
ELECTROLESS NICKEL PLATING BATH COMPOSITION

Title (de)  
STROMLOSE VERNICKELUNGSBADZUSAMMENSETZUNG

Title (fr)  
COMPOSITION DE BAIN DE NICKELAGE AUTOCATALYTIQUE

Publication  
**EP 2737107 B1 20150909 (EN)**

Application  
**EP 12743909 A 20120704**

Priority  

- EP 11175295 A 20110726
- EP 2012062967 W 20120704
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Abstract (en)  
[origin: EP2551375A1] The present invention relates to an aqueous plating bath composition for depositing a nickel phosphorous alloy having a phosphorous content in the range of 5 to 12 wt.-%. The plating bath comprises a sulfur-containing organic stabilising agent.

IPC 8 full level  
**C23C 18/36** (2006.01)

CPC (source: EP US)  
**C23C 18/36** (2013.01 - EP US)

Citation (opposition)  
Opponent : COVENTYA GmbH  

- WO 2010069810 A1 20100624 - BASF SE [DE], et al
- EP 1489201 A2 20041222 - RASCHIG GMBH [DE]
- CH 620710 A5 19801215 - POTAPOV FEDOR PETROVICH, et al
- GB 2155041 A 19850918 - OMI INT CORP
- US 2006264043 A1 20061123 - STEWART MICHAEL P [US], et al
- EP 2551375 A1 20130130 - ATOTECH DEUTSCHLAND GMBH [DE]
- MALLORY ET AL.: "Electroless Plating: Fundamentals and Applications", AMERICAN ELECTROPLATERS AND SURFACE FINISHERS SOCIETY, 1990, pages 1 - 3, XP055290733
- LIU ET AL.: "Effect of organic additives on the corrosion resistance properties of electroless nickel deposits", THIN SOLID FILMS, 11 October 2007 (2007-10-11), pages 1883 - 1889, XP022449729

  
Opponent : Coventya GmbH  

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- US 2006264043 A1 20061123 - STEWART MICHAEL P [US], et al
- EP 2551375 A1 20130130 - ATOTECH DEUTSCHLAND GMBH [DE]
- GLENN O. MALLO RY ET AL.: "Electroless Plating: Fundamentals and Applications", ELECTROLESS PLATING: FUNDAMENTALS AND APPLICATIONS, 1990, XP055290733
- H.-P. LIU ET AL.: "Effect of organic additives on the corrosion resistance properties of electroless nickel deposits", THIN SOLID FILMS, vol. 516, 2008, pages 1883 - 1889, XP022449729

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DOCDB simple family (application)  
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